

NF372-TB Soldering Flux

**THE HIGH-RELIABILITY
FLUX FOR BOTH
THERMALLY
CHALLENGING THIN
AND THICK BOARD
APPLICATIONS**



NF372-TB IS A ZERO-HALOGEN, LOW-SOLIDS, NO-CLEAN LIQUID FLUX FEATURING:

- Wide process preheat window of 90°-140°C (194°-284°F) that accommodates both thin and thick board applications
- High reliability flux that passes both IPC SIR 85/85 and SIR 40/90 and Bono Test for both leaded and lead-free alloys
- Hot bar application
- Pallet process friendly
 - Extends pallet life and does not attack pallet materials
 - The seepage of the flux between pallets and PCB is safer and does not cause reliability issues in condensing or high humidity environment